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# ***Photomask Japan 2017: XXIV Symposium on Photomask and Next-Generation Lithography Mask Technology***

**Kiwamu Takehisa**

*Editor*

**5–7 April 2017**

**Yokohama, Japan**

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The Japan Society of Applied Physics  
The Japan Society for Precision Engineering  
The Institute of Electrical Engineering (Japan)  
Technical Exhibit in Cooperation with SEMI (Japan)

*Supported by*  
City of Yokohama

*Published by*  
SPIE

**Volume 10454**

Proceedings of SPIE 0277-786X, V. 10454

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Photomask Japan 2017: XXIV Symposium on Photomask and Next-Generation Lithography  
Mask Technology, edited by Kiwamu Takehisa, Proc. of SPIE Vol. 10454, 1045401  
© 2017 SPIE · CCC code: 0277-786X/17/\$18 · doi: 10.1117/12.2285890

Proc. of SPIE Vol. 10454 1045401-1

The papers included in this volume were part of the technical conference cited on the cover and title page. Papers were selected and subject to review by the editors and conference program committee. Some conference presentations may not be available for publication. The papers published in these proceedings reflect the work and thoughts of the authors and are published herein as submitted. The publisher is not responsible for the validity of the information or for any outcomes resulting from reliance thereon.

Please use the following format to cite material from these proceedings:

Author(s), "Title of Paper," in *Photomask Japan 2017: XXIV Symposium on Photomask and Next-Generation Lithography Mask Technology*, edited by Kiwamu Takehisa, Proceedings of SPIE Vol. 10454 (SPIE, Bellingham, WA, 2017) Seven-digit Article CID Number.

ISSN: 0277-786X

ISSN: 1996-756X (electronic)

ISBN: 9781510613898

ISBN: 9781510613904 (electronic)

Published by

**SPIE**

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

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